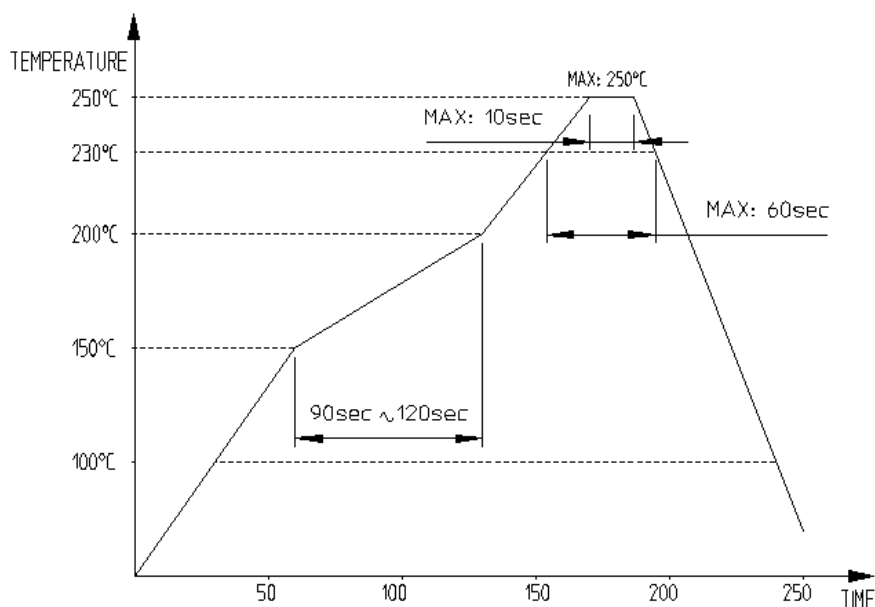


REV	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	REV	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	
①	-	Revised	BJH	LHJ	18.03.16	③	-	Revised	KYG	LHJ	21.08.23	
②	-	Revised	HMY	LHJ	18.04.09	④	-	Revised	KYI	LHJ	21.12.16	
APPLICABLE STANDARD			Universal Serial Bus Type-C Cable and Connector Specification Release 2.1 Universal Serial Bus Type-C Connectors and Cable Assemblies Compliance Document Revision 2.1b									
RATING	CURRENT		1.25A Max. for each power pin (A1, A4, A9, A12, B1, B4, B5, B9, B12) 0.25A for the other pins									
	VOLTAGE		48V AC/DC									
OPERATING CONDITION			-40℃ ~ +105℃ (INCLUDING TEMP. RISE), 95% RH max. (NON-CONDENSING)									
STORAGE CONDITION			-10℃ ~ +60℃ (WITH PACKING), 15% ~ 70% RH									
Para.	Test Description		Test Procedure				Test Requirement				QT	AT
1	Examination of product		EIA 364-18 Visual inspection				No physical damage.				O	O
Electrical Requirements												
2	Low Level Contact Resistance		EIA 364-23 Measure at 20mV max open circuit at 100mA (DC OR 1000Hz). 4-wire measurement is required and the resistance of PCB termination shall be deducted from the reading.				Initial : 40mΩ max for each contact After test : 50mΩ max for each contact				O	-
3	Dielectric Withstanding Voltage		EIA 364-20 Measure per Method B with unmated condition. 100V AC RMS for 1minute at sea level.				No disruptive discharge.				O	-
4	Insulation Resistance		EIA 364-21 500V DC with unmated and mated condition.				100MΩ min.				O	-
Mechanical Requirements												
5	Insertion force		EIA 364-13 Measure at 12.5mm/minute min.				Initial & after test : 5N ~ 20N (with virgin plug)				O	-
6	Extraction force		EIA 364-13 Measure at 12.5mm/minute min.				Initial : 8N ~ 20N After test : 6N ~ 20N (with virgin plug)				O	-
7	Durability		EIA 364-09 Mated 10,000 times Mechanically operated : 500cycles/hr Mating stroke : 2.75mm Insertion, extraction force shall be measured at a maximum speed of 12.5mm/min				No physical damage.				O	-
8	Air-Leak		Input air pressure : 20±5% KPa for 5sec.				Inspection leakage : 0.3% (60Pa) max.				O	-
9	IPX8		Immersion in the water at the depth of 1.5m for 30min.				No water penetration.				O	-
10	Random Vibration		EIA 364-28 Test Condition VII, Test Letter D Mated specimens to 3.10 G's RMS between 20 to 500Hz 15minutes in each of 3 mutually perpendicular planes.				No physical damage. No discontinuity of 1us of longer duration when mated connector during test.				O	-
REMARKS					DRAFT	DESIGN	CHECK	APPROVAL	RELEASE			
					S.H.LIM	S.H.LIM	H.J.LEE	T.S.KANG	DEPT 21.12.16 ENG			
					18.02.19	18.02.19	18.02.19	18.02.19				
NOTE) QT : QUALIFICATION TEST, AT : ASSURANCE TEST, O : Applicable Test												
DWG NO			CL NO				PART NO					
ELC4-632534			CL 6240-0016-6				CX90MWD2-24P					
HRS HIROSE KOREA.CO.,LTD						PRODUCT SPECIFICATION					1/3	

Para.	Test Description	Test Procedure	Test Requirement	QT	AT
Environmental Requirements					
11	Temperature Life	EIA 364-17, Method A 105°C without applied voltage for 120hours.	No physical damage.	O	-
12	Cyclic Temperature and Humidity	EIA 364-31 25±3°C at 80±3% RH for 1hour. 65±3°C at 50±3% RH for 1hour. Thermal ramp : 0.5hour Number of cycles : 24cycles	No physical damage.	O	-
13	Thermal Shock	EIA 364-32, Test Condition I 10cycles -55°C and +105°C	No physical damage.	O	-
14	Solderability	EIA 364-52 Dwell in 245±5°C of the solder bath for 5sec.	Solder coverage shall be 95% min. of the immersed surfaces.	O	-
15	Salt Spray	EIA 364-26 5% of NaCl in 35°C for 48hours.	No corrossions that affect to the connector operation.	O	-
16	Reflow test	Reflow profile [Fig.1] Peak 250°C max for 10sec 2times.	Co-planarity Before & after Reflow 0.08 max. No deformation of mold No shape of blister and popcorn	O	-

REMARKS



[Fig.1] REFLOW TEMPERATURE

NOTE) QT : QUALIFICATION TEST, AT : ASSURANCE TEST, O : Applicable Test

DWG NO ELC4-632534	CL NO CL 6240-0016-6	PART NO CX90MWD2-24P
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HIROSE KOREA.CO.,LTD

PRODUCT SPECIFICATION

Qualification Test Sequence Table											
Para.	Test Description	A	B	C	D	E	F	G	H	I	J
1	Examination of Product	1	1	1	1	1	1	1	1	1	1
2	Low Level Contact Resistance			2,4	2,10	2,4	2,4	2,4		2,4	
3	Dielectric Withstanding Voltage				3,11						
4	Insulation Resistance				4,12						
5	Insertion Force				5,8						
6	Extraction Force				6,9						
7	Durability				7						
8	Air-leak	2									
9	IPX8		2								
10	Random Vibration			3							
11	Temperature Life					3					
12	Cyclic Temperature and Humidity						3				
13	Thermal Shock							3			
14	Solderability								2		
15	Salt Spray									3	
16	Reflow Test										2
Remarks											
1) Numbers in the table above indicate the sequence corresponding to each test group.											